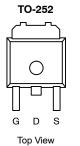


N-Channel 20-V (D-S)175 °C MOSFET

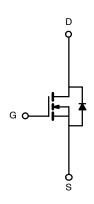
PRODUCT SUMMARY					
V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A) ^a			
20	0.006 @ V _{GS} = 4.5 V	65			
	0.008 @ V _{GS} = 2.5 V	45			

FEATURES

- TrenchFET® Power MOSFET
- 175°C Maximum Junction Temperature
- 100% Rg Tested



Drain Connected to Tab



N-Channel MOSFET

Parameter		Symbol	Limit	
i uluiictei		Cymbol	Linin	Unit
Drain-Source Voltage	V _{DS}	20	v	
Gate-Source Voltage		V _{GS}	±15	V
	$T_{C} = 25^{\circ}C$		65	
Continuous Drain Current ^a	$T_{C} = 100^{\circ}C$		42	
Pulsed Drain Current	I _{DM}	200	— A	
Continuous Source Current (Diode Conduction) ^a	IS	65		
	$T_{C} = 25^{\circ}C$	_	71	
Maximum Power Dissipation	$T_A = 25^{\circ}C$	P _D	8.3 ^{b, c}	w
Operating Junction and Storage Temperature Range		T _J , T _{stq}	-55 to 175	°C

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
	$t \le 10$ sec.		15	18	°C/W		
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	40	50			
Maximum Junction-to-Case		R _{thJC}	1.75	2.1	1		

Notes

- a. Package Limited
- b. Surface Mounted on 1" x 1" FR4 Board

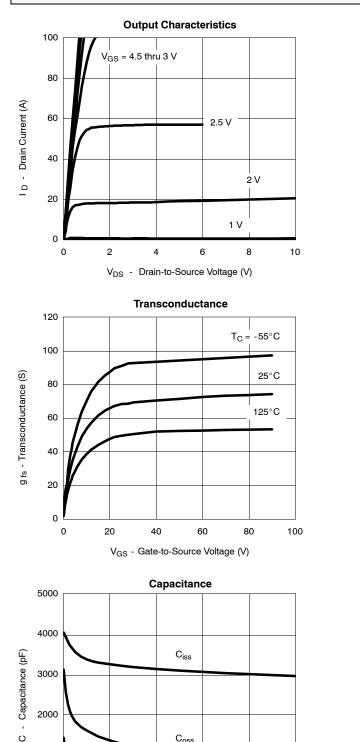
c. $t \leq 10 \text{ sec}$

Parameter	Symbol	Test Condition	Min	Тура	Мах	Unit
Static				1	1	
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V_{GS} = 0 V, I_{D} = 250 μA	20			
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},\ I_D=250\ \mu A$	0.5		1.5	V
Gate-Body Leakage	I _{GSS}	V_{DS} = 0 V, V_{GS} = ±12 V			±100	nA
		V_{DS} = 20 V, V_{GS} = 0 V			1	-μΑ
Zero Gate Voltage Drain Current	IDSS	V_{DS} = 20 V, V_{GS} = 0 V, T_{J} = 125 $^{\circ}C$			50	
On-State Drain Current ^b	I _{D(on)}	V_{DS} = 5 V, V_{GS} = 4.5 V	65			Α
		V_{GS} = 4.5 V, I_D = 20 A		0.0045	0.006	
Drain-Source On-State Resistance ^b	r _{DS(on)}	V_{GS} = 4.5 V, I _D = 20 A, T _J = 125°C		0.0055	0.007	Ω
		V_{GS} = 2.5 V, I_{D} = 20 A		0.006	0.008	1
Forward Transconductanceb	9 _{fs}	V_{DS} = 5 V, I_D = 40 A	20			S
Dynamic ^a			•		•	
Input Capacitance	C _{iss}			3660		pF
Output Capacitance	C _{oss}	V_{GS} = 0 V, V_{DS} = 20 V, f = 1 MHz		730		
Reverse Transfer Capacitance	C _{rss}			375		
Total Gate Charge ^c	Qg			26	35	nC
Gate-Source Charge ^c	Q _{gs}	V_{DS} = 10 V, $\ V_{GS}$ = 4.5 V, I_{D} = 40 A		5		
Gate-Drain Charge ^c	Q _{gd}			7		
Gate Resistance	Rg		1		3.7	Ω
Turn-On Delay Time ^c	t _{d(on)}			20	35	ns
Rise Time ^c	t _r	V _{DD} = 10 V, R _I = 0.25 Ω		120	190	
Turn-Off Delay Time ^c	t _{d(off)}	$\begin{array}{l} V_{DD} = 10 \text{ V}, R_L = 0.25 \ \Omega \\ I_D \ \cong \ 40 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_G = 2.5 \ \Omega \end{array}$		45	70	
Fall Time ^c	t _f			20	35	
Source-Drain Diode Ratings ar	d Characterist	tic (T _C = 25°C)	•			
Pulsed Current	I _{SM}				100	А
Diode Forward Voltage ^b	V _{SD}	I _F = 100 A, V _{GS} = 0 V		1.2	1.5	V
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 40 A, di/dt = 100 A/μs		35	70	ns

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TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)



Coss

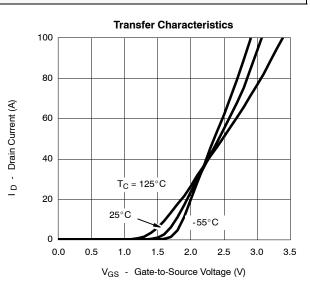
V_{DS} - Drain-to-Source Voltage (V)

12

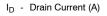
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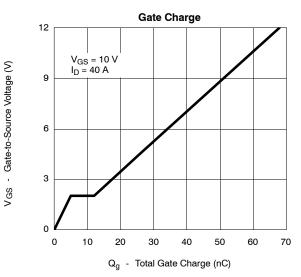
20

8



On-Resistance vs. Drain Current 0.012 $r_{DS(on)}$ - On-Resistance (Ω) 0.009 V_{GS} = 2.5 V 0.006 $V_{GS} = 4.5 V$ 0.003 0.000 0 20 40 60 80 100





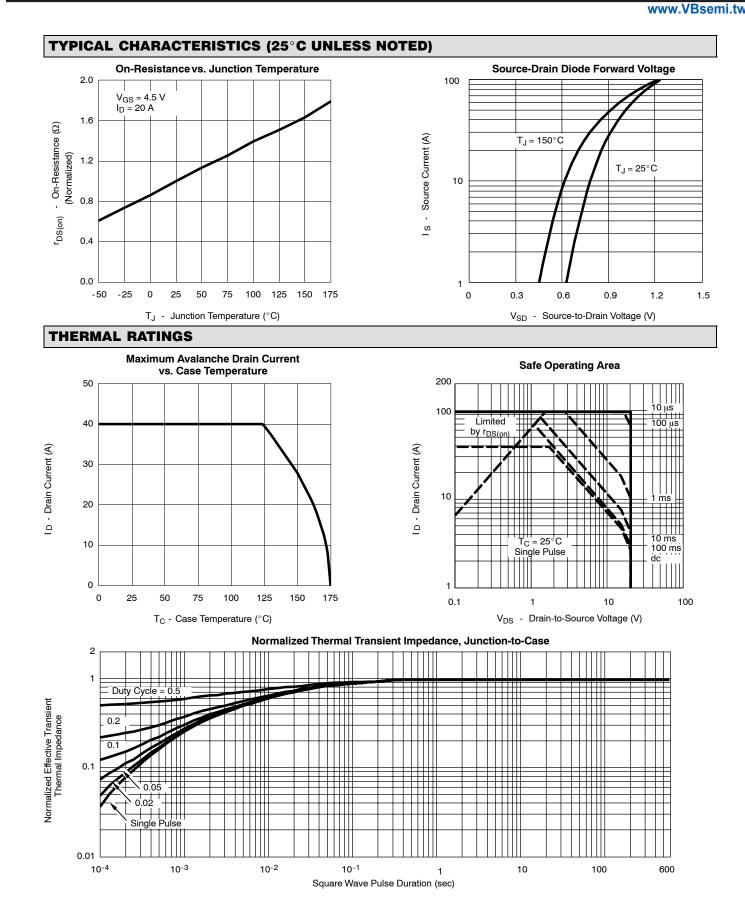
C_{rss}

4

1000

0

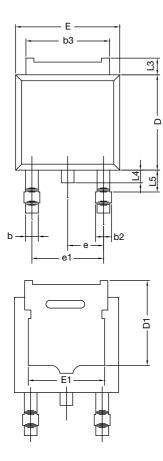
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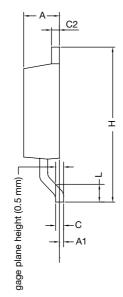


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TO-252AA CASE OUTLINE





	MILLIMETERS		INC	INCHES		
DIM.	MIN.	MAX.	MIN.	MAX.		
А	2.18	2.38	0.086	0.094		
A1	-	0.127	-	0.005		
b	0.64	0.88	0.025	0.035		
b2	0.76	1.14	0.030	0.045		
b3	4.95	5.46	0.195	0.215		
С	0.46	0.61	0.018	0.024		
C2	0.46	0.89	0.018	0.035		
D	5.97	6.22	0.235	0.245		
D1	5.21	-	0.205	-		
E	6.35	6.73	0.250	0.265		
E1	4.32	-	0.170	-		
Н	9.40	10.41	0.370	0.410		
е	2.28 BSC		0.090	BSC		
e1	4.56 BSC		0.180 BSC			
L	1.40	1.78	0.055	0.070		
L3	0.89	1.27	0.035	0.050		
L4	-	1.02	-	0.040		
L5	1.14	1.52	0.045	0.060		
ECN: X12-0247-Rev. M, 24-Dec-12 DWG: 5347						

Note

• Dimension L3 is for reference only.



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